



Material Content Data Sheet



Sales Product Name		BCR 512 E6327		Issued		29. August 2013			
MA#		MA000240790							
Package		PG-SOT23-3-4		Weight*		9.08 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	non noble metal	arsenic	7440-38-2	0.000	0.00		15		
	noble metal	gold	7440-57-5	0.013	0.14		1439		
	inorganic material	silicon	7440-21-3	0.112	1.23	1.37	12288	13742	
leadframe	non noble metal	chromium	7440-47-3	0.009	0.10		996		
	inorganic material	silicon	7440-21-3	0.001	0.01		66		
	non noble metal	titanium	7440-32-6	0.003	0.03		332		
	non noble metal	copper	7440-50-8	3.001	33.05	33.19	330528	331922	
wire	noble metal	gold	7440-57-5	0.017	0.18	0.18	1823	1823	
	encapsulation	organic material	carbon black	1333-86-4	0.091	1.00		10006	
		inorganic material	antimonytrioxide	1309-64-4	0.136	1.50		15010	
		plastics	brominated resin	-	0.170	1.88		18762	
		plastics	epoxy resin	-	1.419	15.64		156351	
		inorganic material	silicondioxide	60676-86-0	3.861	42.53	62.55	425275	625404
leadfinish	non noble metal	tin	7440-31-5	0.136	1.50	1.50	15026	15026	
plating	noble metal	silver	7440-22-4	0.110	1.21	1.21	12083	12083	
*deviation	< 10%		Sum in total:			100,00		1000000	

Important Remarks:

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Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com